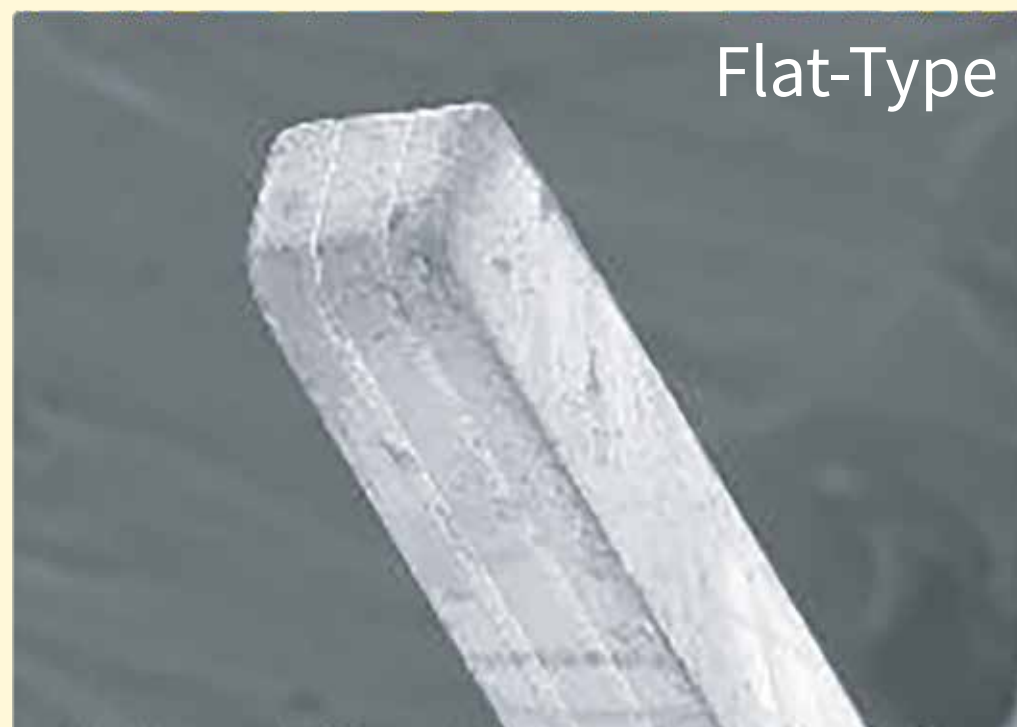
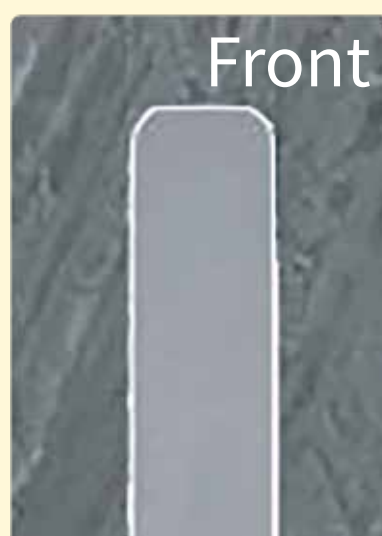


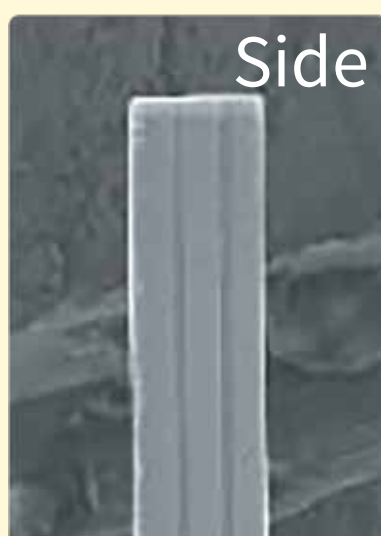
プリント基板&半導体パッケージ基板検査システム用 For printed circuit board and semiconductor package inspection system



Flat-Type



Front



Side



Point-Type



Front



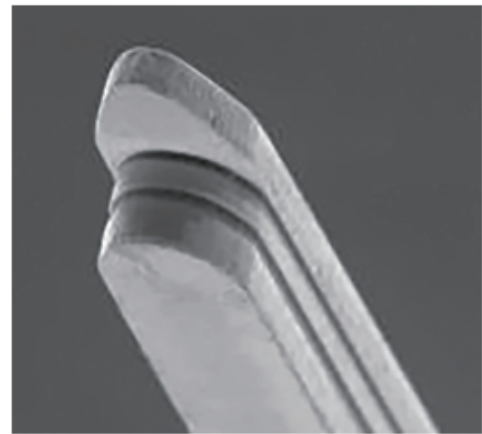
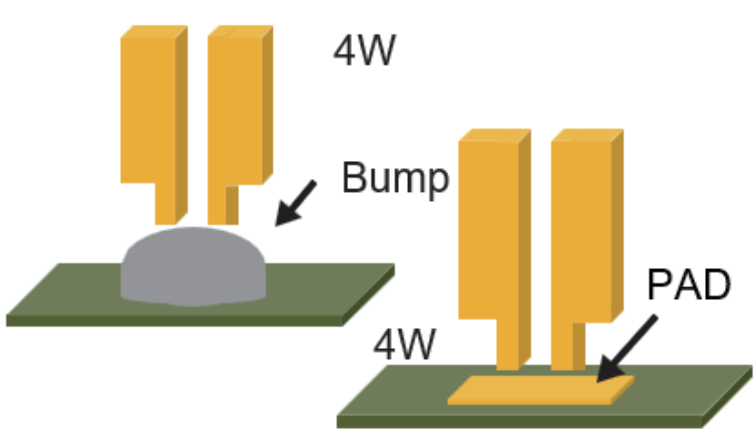
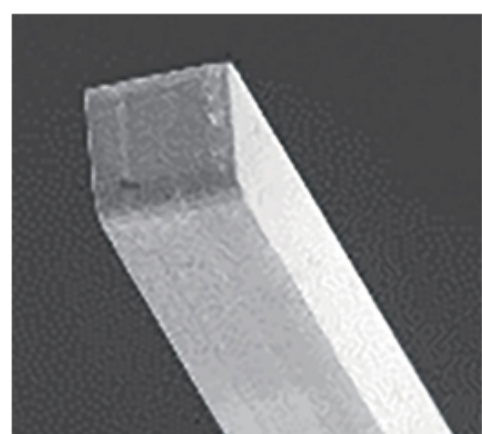
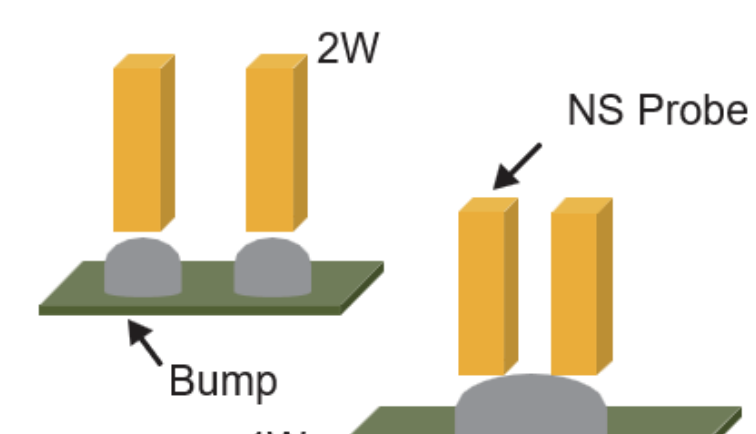
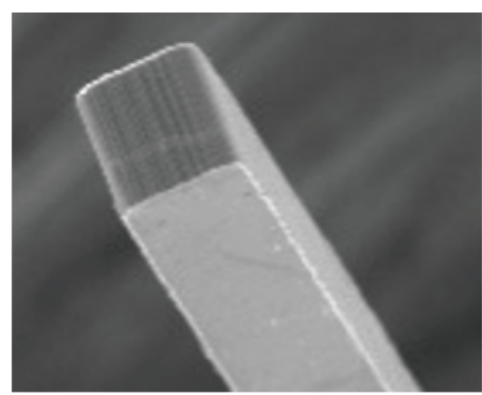
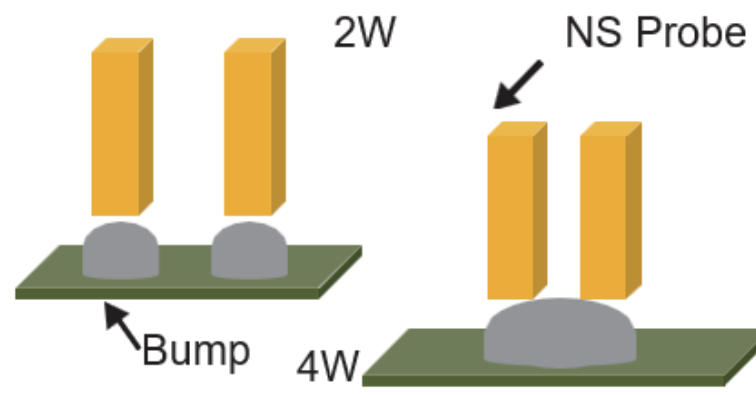
Side

寸法精度の向上 | Good tolerance

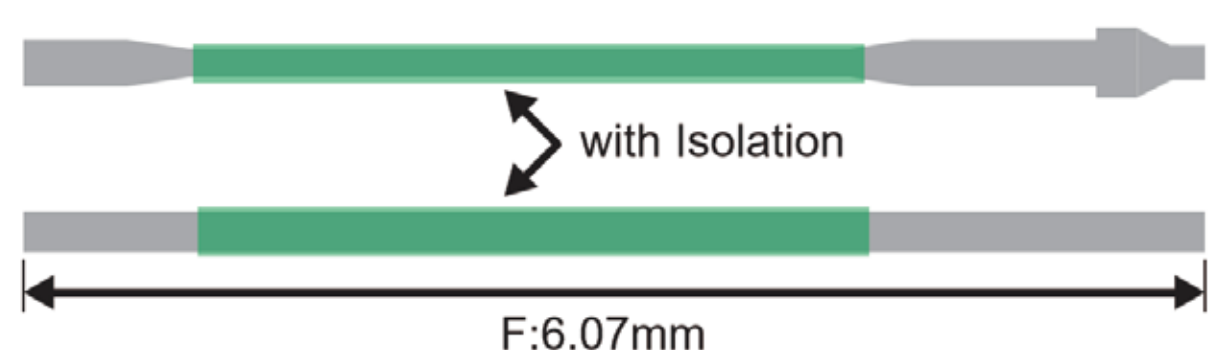
材料選定が可能 | Select the body metal

MEMSプロセスを用いた微細化・先端形状の多様化を実現したプローブを開発
We developed the new probe that used MEMS process for min Pitch and possible to make various tip shape.

NS probe specifications

Probe Type	2W Pitch	4W Pitch	Tip Size	Force	Stroke	Raw Material	Contact Images
	55 μ m	Bump Pitch 100 μ m Probe Pitch 35 μ m	28 $\times$ 25 μ m	1.0gf	60 μ m	PdCo/Cu Isolation Coat Au Surface	
	45 μ m	Bump Pitch 80 μ m Probe Pitch 45 μ m	20 $\times$ 22 μ m	0.8gf	60 μ m	PdCo/Cu Isolation Coat Au Surface	
	35 μ m	Bump Pitch 55 μ m Probe Pitch 35 μ m	13 $\times$ 12 μ m	0.4gf	60 μ m	PdCo/Au Isolation Coat	

Flat



Point

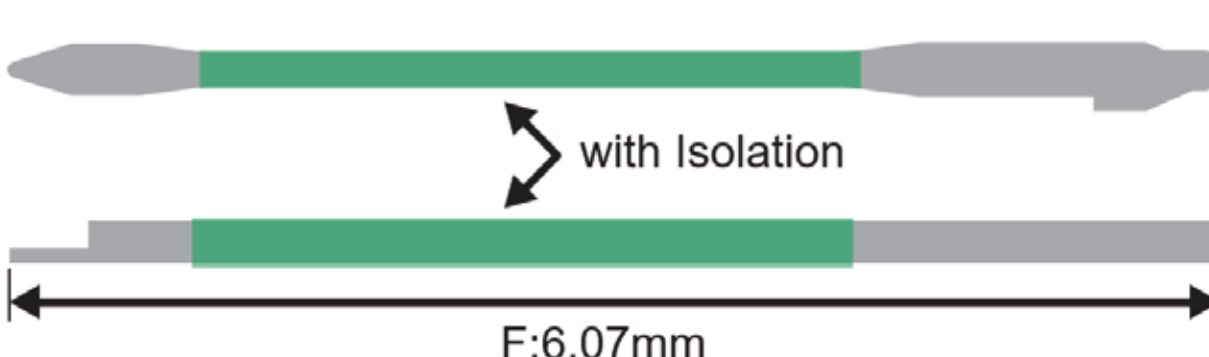
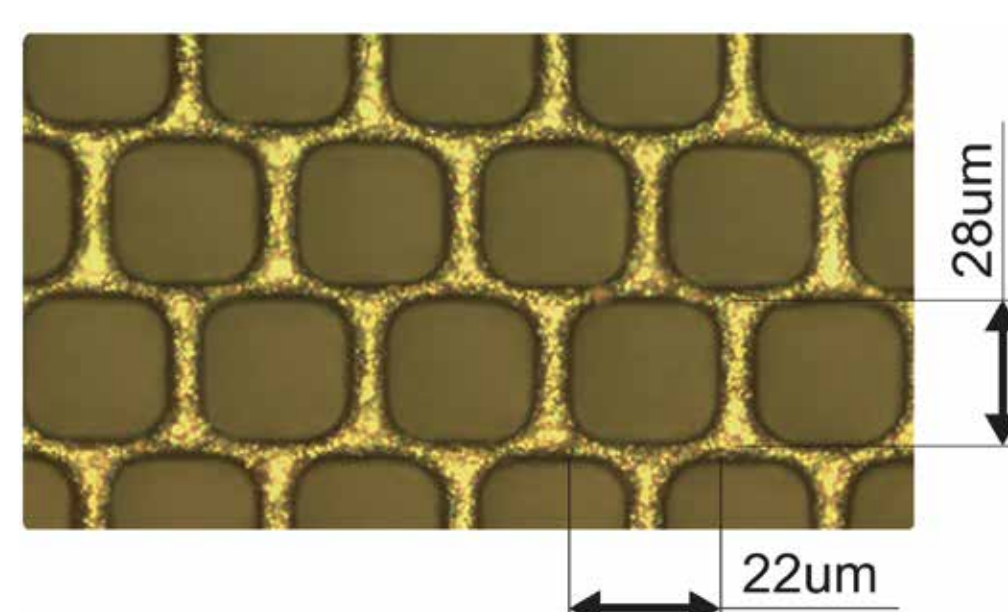


Plate processing



国内拠点

・京都(本社)
617-0007 京都府向日市ニデックパーク33番地C棟
TEL 075-280-8101 / FAX 075-280-8106
・名古屋
503-0974 岐阜県大垣市久瀬川町1-3
TEL 0584-83-7680 / FAX 0584-83-7685
・東京
141-0032 東京都品川区大崎1丁目20番13号 Nidec東京ビル
TEL 03-3494-7970 / FAX 03-3494-0793

海外拠点

・台湾 NIDEC ADVANCE TECHNOLOGY TAIWAN CORPORATION
・韓国 NIDEC ADVANCE TECHNOLOGY KOREA CO., LTD.
・中国 NIDEC ADVANCE TECHNOLOGY ZHEJIANG CORPORATION
・タイ NIDEC ADVANCE TECHNOLOGY THAILAND CO., LTD.
・マレーシア NIDEC ADVANCE TECHNOLOGY MALAYSIA SDN. BHD.
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・インド NIDEC ADVANCE TECHNOLOGY INDIA PRIVATE LIMITED
・カナダ NIDEC ADVANCE TECHNOLOGY CANADA CORPORATION